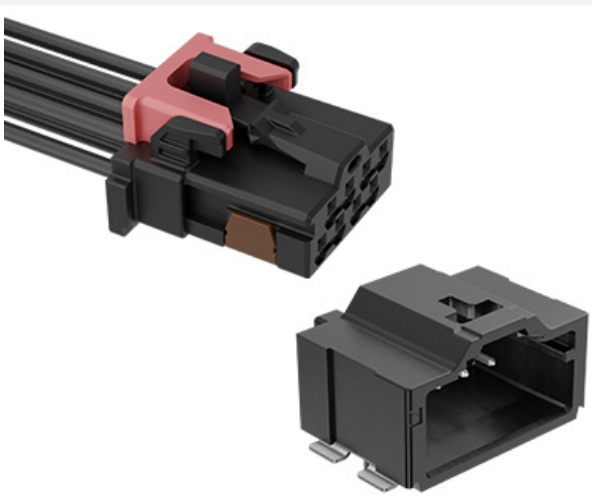
MicroSpaceXS™ 1.27 mm Unsealed Enhanced Crimp–to–Wire Connector Platform

COMPACT, ROBUST AND VERSATILE CONNECTOR SYSTEM

MicroSpaceXS™ Crimp–to–Wire connector platform's unique design meets up to USCAR–T4V2 specifications. These 1.27 mm pitch connectors come with a current rating up to 4 A per contact making them ideal for higher power applications. MicroSpaceXS™ connectors are available in staggered pin configuration horizontal orientations and in Wire–to–Board configurations. These connectors are offered in tin and gold plating.

MicroSpaceXS™ Crimp–to–Wire connector platform has a compact 1.27 mm pitch designed to meet up to USCAR–T4V2 requirements. The system supports current ratings up to 4 A per contact, making it suitable for higher–power automotive applications. MicroSpaceXS™ connectors are available in staggered pin configurations, horizontal orientations, and wire–to–board configurations. The platform incorporates Terminal Positioning Assurance (TPA), Connector Positioning Assurance (CPA), and primary and secondary contact retention features. Connectors are offered with tin or gold plating options.

- Up to USCAR–T4V2
- Design improved to meet USCAR 2, USCAR 12, and USCAR 25
- Terminal Positioning Assurance (TPA)
- Primary and secondary contact retention
- Connector Positioning Assurance (CPA)



TARGET MARKETS



FEATURES

- Mechanical Connector Position Assurance (CPA)
- Terminal Position Assurance (TPA)
- Poka–Yoke polarization and color coding
- Current rating up to 4 A per contact
- 4 N normal force for vibration > 75 N connector locking strength
- USCAR–2 / USCAR–12 / USCAR–25 compliance

BENEFITS

- Ensures proper mating of the header and receptacle and avoids unintentional triggering of the latch
- Ensures proper terminal insertion position and retention
- Prevents visual mismatch
- Meets higher power performance requirements
- High vibration and locking resistance
- Designed ergonomically to enhance user comfort, facilitate easy disassembly, and ensure greater durability

TECHNICAL INFORMATION

MATERIAL

- Contact: High current Alloy with optional Tin and Gold plating
- Housing: High–temperature thermoplastic, UL 94 V–0 CTI>600
- Platings:
  - Tin (Sn): 3µ
  - Gold (Au): 0.76µ

ELECTRICAL PERFORMANCE

- Current Rating: 4 A
- Voltage Rating: 12 V – 48 V
- Low Level Contact Resistance: <30 mΩ
- Insulation Resistance: >100 mΩ
- Dielectric Withstanding Voltage: 500 V AC
- Temperature Rise: 30°C max.

MECHANICAL PERFORMANCE

- Terminal Insertion Force/Terminal: <3 N
- Low Insertion Force Terminal:(<2 N) available upon request
- Terminal Retention into Housing: >40 N
- Durability:
  - 20 mating cycles for Sn
  - 100 mating cycles for Au

SPECIFICATIONS

- Product Specification: GS–12–2109
- Packaging Specification: GS–14–2777

ENVIRONMENTAL

- Operating Temperature Range:
  - –40°C to +105°C for Sn
  - –40°C to +150°C for Au
- UL 94 V–0

APPROVALS AND CERTIFICATIONS

- Tin plating: USCAR–T2V2
- Gold plating: USCAR–T4V2
- VW75174 – Slow Motion Bending Test
- VW60330 – Crimp specification
- USCAR – 2 / –12 / –25

PACKAGING

- PCB Header WtB: Tape & Reel
- Receptacle Housing: Bag
- Terminal: Reel

TARGET MARKETS/APPLICATIONS



Lighting
Camera / Sensor
Infotainment
HVAC
Battery Management



Automotive Lighting

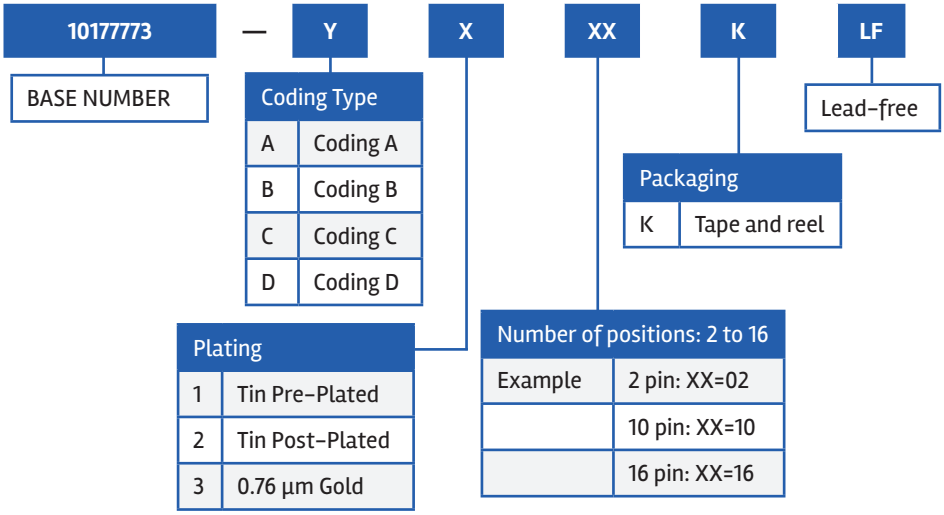
PART NUMBERS

Description	Part Numbers
MicroSpaceXS™ Header Horizontal Top latch Enhanced	10177773
MicroSpaceXS™ Receptacle Top latch Enhanced	10155546
MicroSpaceXS™ Terminals	10155447

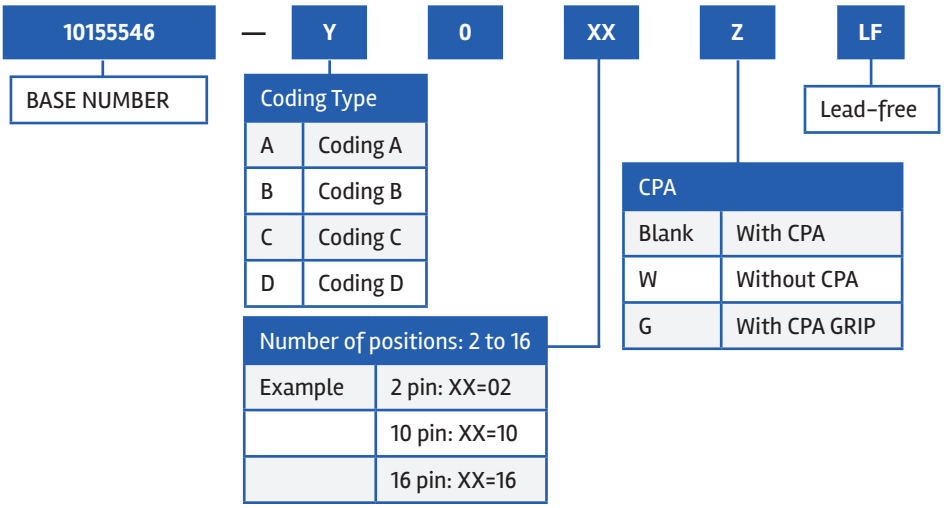
Find part number details using the search box on www.amphenol–cs.com

Disclaimer
Please note that the above information is subject to change without notice.

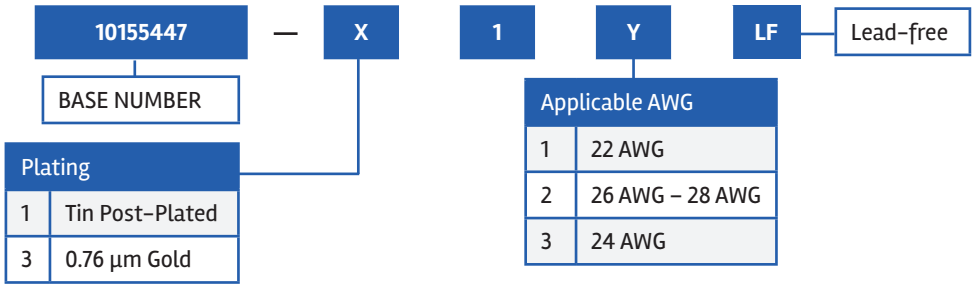
PART NUMBER SELECTOR – HEADER



PART NUMBER SELECTOR – RECEPTACLE



PART NUMBER SELECTOR – TERMINALS



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